

Abstract

Support with solder ball elements and a method for loading substrates with ball contacts

The invention relates to a support (4) with solder ball elements (1) for loading substrates (2) with ball contacts. Furthermore, the invention relates to a system for loading substrates (2) with ball contacts and to a method for loading substrates (2) with ball contacts. For this purpose, the support (4) has a layer of adhesive (5) applied on one side, the layer of adhesive (5) losing its adhesive force to the greatest extent when irradiated. Furthermore, the support (4) has solder ball elements (1), which are arranged closely packed in rows (6) and columns (7) on the layer of adhesive (5) in a prescribed pitch (w) for a semiconductor chip or a semiconductor component.

[Figure 1]